



Product Change Notification

Current Date: 28-Oct-2015

TE Connectivity

Product Change Notification: E-15-010060

PCN Date: 26-OCT-15

Customer: Newark Electronics (167839)

Location: Chicago

Agreement: Agreement Unknown

TE would like to inform you of the following change(s) to the listed TE Connectivity Product. In case of any further questions about this change(s), please contact your TE Connectivity Sales Engineer. Affected part, drawing and/or specification numbers are listed on the attached sheet(s).

General Product Description:

QSFP cable assembly

Description of Changes

TE Connectivity is standardizing the type of plating used on all high speed IO cable assembly products. Products include HSSDC2, SFP, QSFP, Mini SAS, Mini SAS HD and associated derivatives. Plug module shells currently using Tin plating will be converted to Nickel plating.

Reason for Changes:

Product Improvement. Nickel plating is the most widely used type of plating in the industry for high speed cable assembly plug modules. Nickel plating provides a more consistent appearance

Estimated Dates:

Last Order Date (Obsolete Parts Only):

First Date To Ship (Changed Parts Only):

19-JAN-2016

Last Ship Date (Obsolete Parts Only):

Last Date for Mixed Shipments: (Changed Parts Only):

30-JAN-2016

Part Number(s) being Modified:

Part Number	Part Discontinued per PCN	Customer Drawing	Customer Part Number	Alias Part Number(s)	Substitute Part Number	Substitute Alias Part Number(s)	Description Of Difference
2053453-2	NO						
2053453-4	NO						